

ESL ELECTROSCIENCE

CERAMIC TAPES & THICK-FILM MATERIALS 416 EAST CHURCH ROAD KING OF PRUSSIA, PA 19406-2625, U.S.A

www.electroscience.com

5837-G **CERMET PLATINUM / GOLD CONDUCTOR**

RoHS Compliant*

ESL 5837-G is a platinum / gold conductor that is solderable both on 96% alumina substrates and when fired over 4913 and 4920 dielectrics. The 5837-G can be used in high reliability multilayer circuits where chip carriers are soldered to the top layer. The re-fire capability on alumina is also high. A typical lead and cadmium-free system consists of 8844-G gold conductor, 4913 dielectric and 5837-G. The 5837-G can also be used on beryllia substrates with excellent initial adhesion. However, the aged adhesion is lower than that obtained on 96% alumina substrates. This may be improved by firing at 980°C.

PASTE DATA

Rheology:

Thixotropic, screen-printable paste

Viscosity: (Brookfield RVT, 10rpm, ABZ spindle, 25.5 ± 0.5 °C)

Bonding Mechanism: Shelf Life (20 - 25 °C):

PROCESSING

350 ± 25 Pa.s Mixed-bonded 6 months

Screen Mesh, Emulsion: 325 S/S, 20 µm Levelling Time (at 20°C): 5 - 10 min 10 -15 min Drying Time (at 125°C): 850 - 1000°C in air **Firing Temperature Range:** Optimum: Time at peak: **Total Firing Cycle:** 96% alumina Substrate for Calibration:

Thinner:

ESL Europe 5837-G 0609-E

ESL 401

850°C

10 min

1 hour

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TYPICAL PROPERTIES

Fired Thickness: (measured on a 2 mm x 2 mm pad on 96% alumin	na)	12	2.0 ± 2.0 µm
Approximate Coverage:		5	5 - 70 cm²/g
Resistivity: (measured on a 100 mm x 0.25 mm conductor tra	ack)		< 85 mΩ/□
Printing Resolution: (line/space)		0.125 mm	/ 0.125 mm
Solder Wettability: (RMA flux, 5 sec. dip, 95.5Sn/3.8Ag/0.7Cu, 250°C)	on 96% alu over 4913 over 4920	ımina	95 - 100 % 90 - 95 % 90 - 95 %
Solder Leach: (No. of 10 sec. dips to double lowest resistance of 100 mm x 0.25 mm conductor, 95.5Sn/3.8Ag/0.70			> 6 dips
Adhesion: (90° pull, 2 mm x 2 mm pads, 95.5Sn/3.8Ag/0.7C Initial pull stree Aged 48 hours	ngth:	on 96% alumina on 96% alumina	> 7.0 kg > 4.0 kg

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*None of the six substances referred to in the RoHS Directive (2002/95/EC) are used in the formulation of this product.

CAUTION: Proper industrial safety precautions should be exercised in using these products. Use with adequate ventilation. Avoid prolonged contact with skin or inhalation of any vapours emitted during use or heating of these compositions. The use of safety eye goggles, gloves or hand protection creams is recommended. Wash hands or skin thoroughly with soap and water after using these products. Do not eat or smoke in areas where these materials are used. Refer to appropriate MSDS sheet.

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